CHIPQUIK®

Datasheet revision 1.0 www.chipquik.com

Chip Removal Alloy (2 feet, 3.175mm THICK Diameter) for SMD/SMT (4-6.5" sticks)

Product Highlights

Easily remove SMD parts with **Chip Quik**® removal alloy Reduce heat and reduce damage to circuit boards and SMD parts during removal Comes with SMDLT flux

Specifications

Alloy: Chip Quik® Alloy Leaded 4-6.5in. Thick Sticks

Alloy Melting Point: 58°C (136°F) Thickness: 3.175mm (0.125")

Flux: SMDLT 2cc/2g Squeeze Tube

Flux Type: No-Clean Flux Classification: REL0

Flux Activation Temperature: 100°C (212°F)



Chip Quik® Instructions		
	1	Apply Chip Quik flux to all leads of SMD with syringe or flux applicator.
	2	Melt Chip Quik low temperature alloy uniformly on all pins of SMD. Maintain alloy in molten state long enough for complete reflow.
	3	Lift chip from board with dental pick or vacuum pen.
	4	Thoroughly clean site with swab dipped in flux while applying heat. Clean thoroughly with alcohol pad.

SMD Removal

(With solder iron or warm air bath)

- Apply flux to all leads.
- Melt CHIP QUIK® uniformly on all pins.
- Maintain alloy in molten state long enough to release chip.
- Lift chip from board with dental pick or vacuum pen.

CLEAN UP

- While molten, use cotton swab and flux to move excess to an unused section of board.
- While applying heat, polish each pad with a swab and flux until thoroughly clean.
- At room temperature, clean residue with alcohol pad.
- You are now ready to install the new chip.

6.5" of thick sticks of Chip Quik® material, removes 1,250 to 1,500 SMD pins.

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): RoHS 3 Directive (EU) 2015/863:

Yes No